# NPN Silicon Power Transistor

## **DPAK for Surface Mount Applications**

Designed for general purpose amplifier and low speed switching applications.

#### **Features**

- High Gain
- Low Saturation Voltage
- High Current Gain Bandwidth Product
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

| Rating  | Symbol                            | Value         | Unit      |
|---|-----------------------------------|---------------|-----------|
| Collector–Emitter Voltage   | V <sub>CEO</sub>                  | 45            | Vdc       |
| Collector-Base Voltage  | V <sub>CB</sub>                   | 45            | Vdc       |
| Emitter-Base Voltage  | V <sub>EB</sub>                   | 5.0           | Vdc       |
| Collector Current – Continuous  | I <sub>C</sub>                    | 4.0           | Adc       |
| Collector Current – Peak  | I <sub>CM</sub>                   | 7.0           | Adc       |
| Base Current  | I <sub>B</sub>                    | 50            | mAdc      |
| Total Power Dissipation  @ T <sub>C</sub> = 25°C  Derate above 25°C         | P <sub>D</sub>                    | 20<br>0.16    | W<br>W/°C |
| Total Power Dissipation (Note 1)  @ T <sub>A</sub> = 25°C Derate above 25°C | P <sub>D</sub>                    | 1.75<br>0.014 | W<br>W/°C |
| Operating and Storage Junction<br>Temperature Range                         | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150   | °C        |
| ESD – Human Body Model  | HBM                               | HBM 3B        |           |
| ESD – Machine Model   | MM                                | С             | V         |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

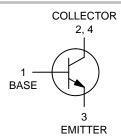
 These ratings are applicable when surface mounted on the minimum pad sizes recommended.



#### ON Semiconductor®

http://onsemi.com

## POWER TRANSISTOR 4.0 AMPERES 45 VOLTS, 20 WATTS





DPAK CASE 369C STYLE 1

#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year

WW = Work Week

J148 = Device Code

G = Pb-Free Package

#### ORDERING INFORMATION

| Device       | Package           | Shipping <sup>†</sup> |
|--------------|-------------------|-----------------------|
| MJD148T4G    | DPAK<br>(Pb-Free) | 2,500/Tape & Reel     |
| NJVMJD148T4G | DPAK<br>(Pb-Free) | 2,500/Tape & Reel     |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### THERMAL CHARACTERISTICS

| Characteristic                                   | Symbol         | Max  | Unit |
|--|----------------|------|------|
| Thermal Resistance, Junction-to-Case             | $R_{	heta JC}$ | 6.25 | °C/W |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{	heta JA}$ | 71.4 | °C/W |

<sup>2.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25$ °C, unless otherwise noted)

| Characteristic  | Symbol                | Min                  | Max                | Unit |
|---|-----------------------|----------------------|--------------------|------|
| OFF CHARACTERISTICS   | ·                     |                      |                    |      |
| Collector–Emitter Sustaining Voltage (Note 3) (I <sub>C</sub> = 100 mAdc, I <sub>B</sub> = 0)     | V <sub>CEO(sus)</sub> | 45                   | _                  | Vdc  |
| Collector Cutoff Current<br>(V <sub>CB</sub> = 45 Vdc, I <sub>E</sub> = 0)                        | I <sub>CBO</sub>      | _                    | 20                 | μAdc |
| Emitter Cutoff Current (V <sub>BE</sub> = 5 Vdc, I <sub>C</sub> = 0)                              | I <sub>EBO</sub>      | -                    | 1                  | mAdc |
| ON CHARACTERISTICS (Note 3)   | <u>.</u>              |                      |                    |      |
| DC Current Gain   | h <sub>FE</sub>       | 40<br>85<br>50<br>30 | -<br>375<br>-<br>- | -    |
| Collector–Emitter Saturation Voltage (I <sub>C</sub> = 2 Adc, I <sub>B</sub> = 0.2 Adc)           | V <sub>CE(sat)</sub>  | -                    | 0.5                | Vdc  |
| Base–Emitter On Voltage<br>(I <sub>C</sub> = 2 Adc, V <sub>CE</sub> = 1 Vdc)                      | V <sub>BE(on)</sub>   | -                    | 1.1                | Vdc  |
| DYNAMIC CHARACTERISTICS   | ·                     |                      | •                  | •    |
| Current–Gain–Bandwidth Product<br>(I <sub>C</sub> = 250 mAdc, V <sub>CE</sub> = 1 Vdc, f = 1 MHz) | f <sub>T</sub>        | 3                    | -                  | MHz  |

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2%.

#### TYPICAL CHARACTERISTICS

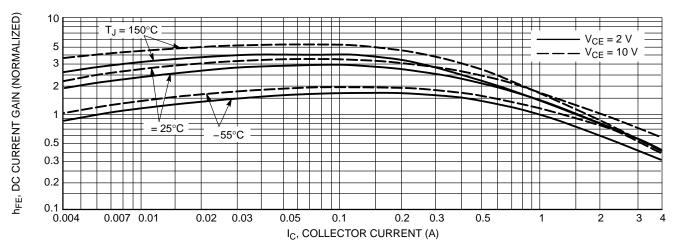


Figure 1. DC Current Gain

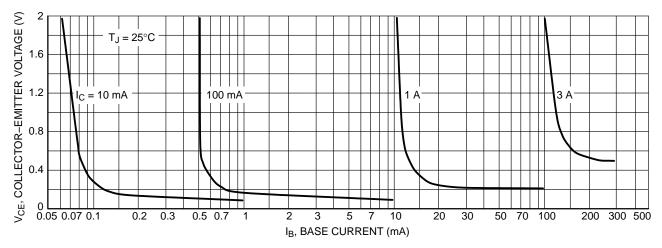
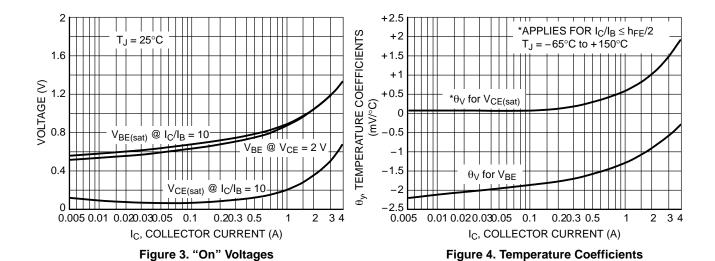


Figure 2. Collector Saturation Region



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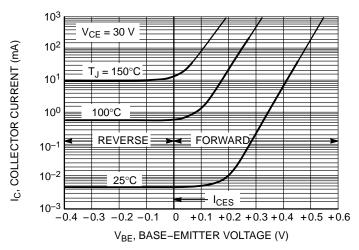


Figure 5. Collector Cut-Off Region

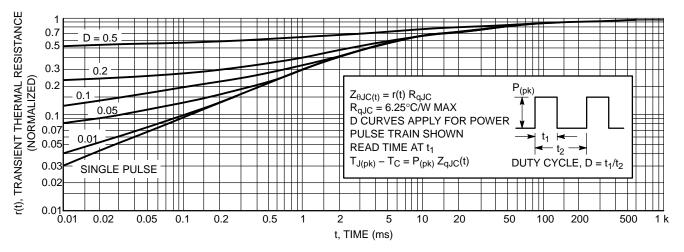


Figure 6. Thermal Response

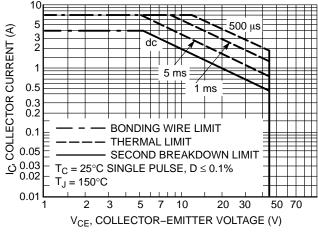


Figure 7. Maximum Rated Forward Bias

#### Forward Bias Safe Operating Area Information

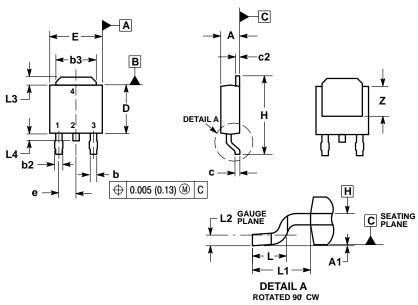
There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 7 is based on  $T_{J(pk)} = 150^{\circ}C$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 6. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

#### PACKAGE DIMENSIONS

#### **DPAK (SINGLE GAUGE)**

CASE 369C ISSUE D



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
   TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- NOT EXCEED 0.006 INCHES PER SIDE.

  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
  6. DATUMS A AND B ARE DETERMINED AT DATUM

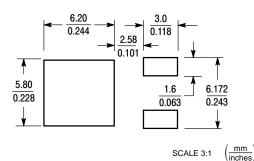
|     | INCHES    |       | MILLIMETERS |       |  |
|-----|-----------|-------|-------------|-------|--|
| DIM | MIN       | MAX   | MIN         | MAX   |  |
| Α   | 0.086     | 0.094 | 2.18        | 2.38  |  |
| A1  | 0.000     | 0.005 | 0.00        | 0.13  |  |
| b   | 0.025     | 0.035 | 0.63        | 0.89  |  |
| b2  | 0.030     | 0.045 | 0.76        | 1.14  |  |
| b3  | 0.180     | 0.215 | 4.57        | 5.46  |  |
| С   | 0.018     | 0.024 | 0.46        | 0.61  |  |
| c2  | 0.018     | 0.024 | 0.46        | 0.61  |  |
| D   | 0.235     | 0.245 | 5.97        | 6.22  |  |
| Е   | 0.250     | 0.265 | 6.35        | 6.73  |  |
| е   | 0.090 BSC |       | 2.29 BSC    |       |  |
| Н   | 0.370     | 0.410 | 9.40        | 10.41 |  |
| L   | 0.055     | 0.070 | 1.40        | 1.78  |  |
| L1  | 0.108 REF |       | 2.74 REF    |       |  |
| L2  | 0.020     | BSC   | 0.51 BSC    |       |  |
| L3  | 0.035     | 0.050 | 0.89        | 1.27  |  |
| L4  |           | 0.040 |             | 1.01  |  |
| Z   | 0.155     |       | 3.93        |       |  |

STYLE 1: PIN 1. BA

PIN 1. BASE 2. COLLECTOR

3. EMITTER 4. COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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